SUBMINIATURE SOLID STATE LAMP

Part Number: AM27EC03

High Efficiency Red

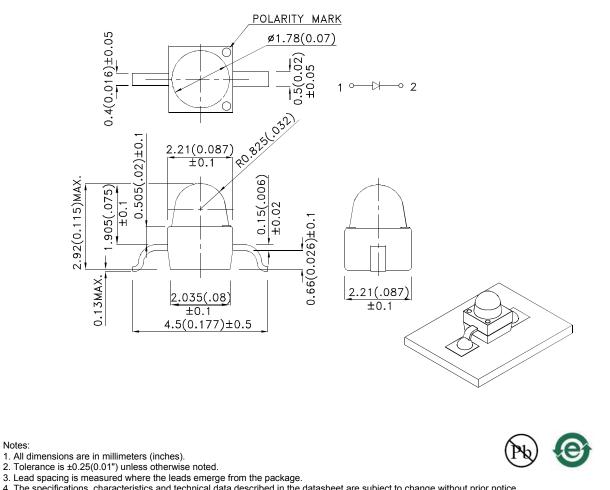
Features

- Subminiature package.
- Gull wing.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- · RoHS compliant.

Package Dimensions

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.



4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. 5. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAB5748 **APPROVED: WYNEC**

Notes:

REV NO: V.8 **CHECKED: Allen Liu** DATE: APR/14/2011 DRAWN: J.Yu

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Selection Guide

Part No.	Dice	Lens Type		· • •	Viewing Angle [1]
			Min.	Тур.	201/2
AM27EC03	High Efficiency Red (GaAsP/GaP)	Water Clear	50	100	20°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	Vr=5V

Notes:

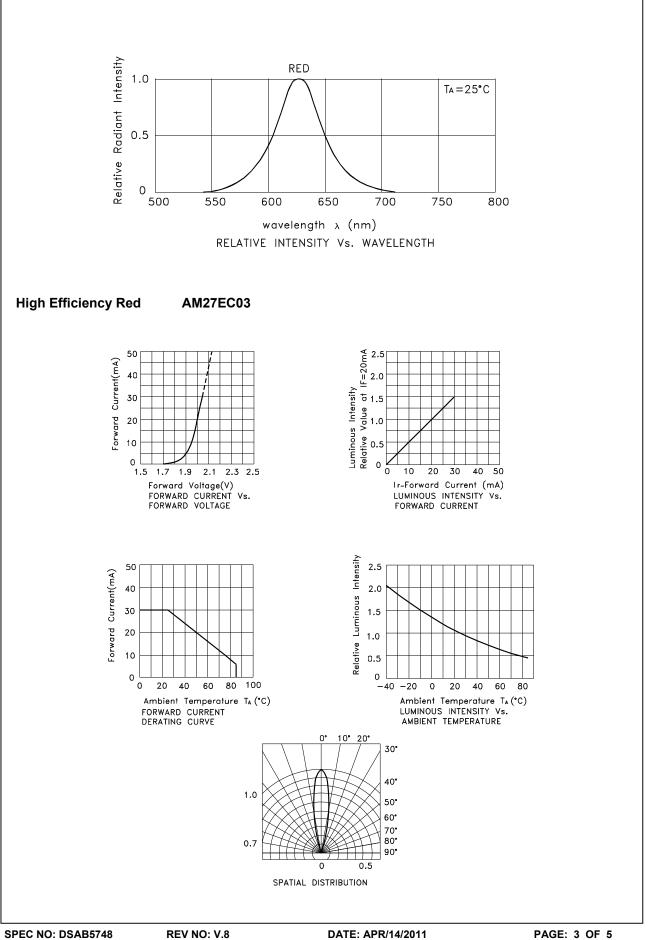
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

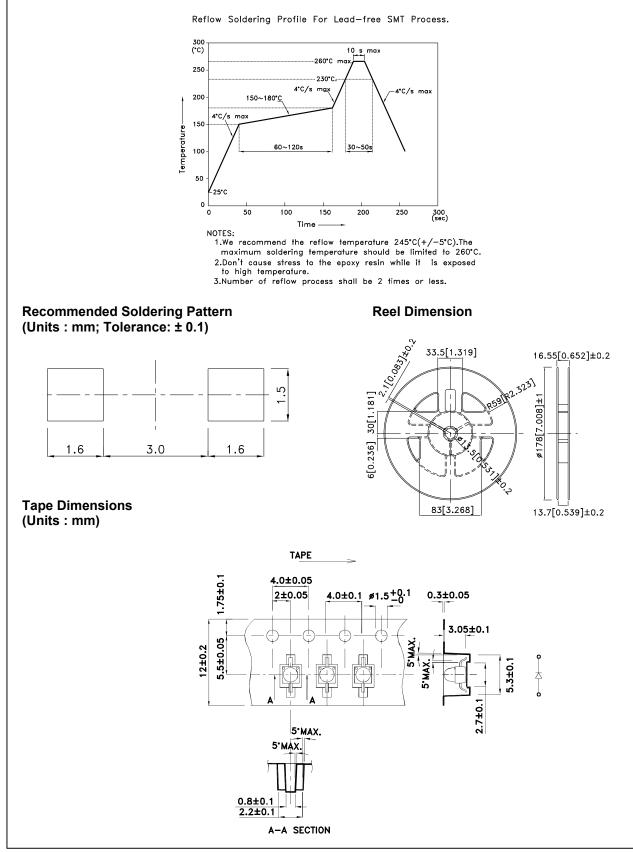
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AM27EC03

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



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